



## Discription

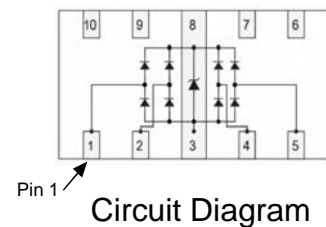
The HCESD2510LC5VU-M is a 4-channel ultra low capacitance rail clam ESD protection diodes array . Each channel consists of a pair of diodes that steer positive or negative ESD current to either the positive or negative rail . A zener diode is integrated in to the array between the positive and negative supply rails. In the typical applications, the negative rail pin (assigned as GND) is connected with system ground . The Positive ESD current is steered to the ground through an ESD diode and Zener diode and the positive ESD voltage is clamped to the zener voltage.



DFN2510-10L

## Features

- ★ 4 channels of ESD protection;
- ★ Provides ESD protection to IEC61000-4-2 level 4
  - ±25kV air discharge
  - ±20kV contact discharge;
- ★ Ultra-low Capacitance:0.4pF(Typical)
- ★ Low clamping voltage;
- ★ Low operating voltage;
- ★ Solid-state silicon technology
- ★ Protecting four I/O line
- ★ RoHS compliant and Halogen Free.



## Ordering information

Product ID	Pack	Qty(PCS)
HCESD2510LC5VU-M	DFN2510-10L	3000

## Absolute Ratings(Tamb = 25°C)

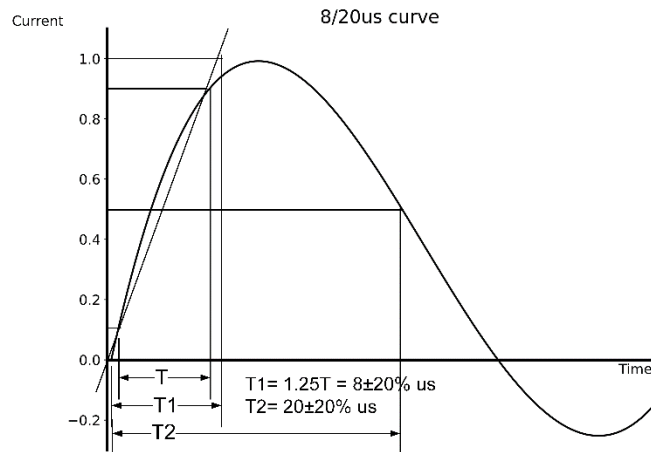
Symbol	Parameter	Value	Units	
P <sub>PP</sub>	Peak Pulse Power (t <sub>p</sub> = 8/20μs)	50	W	
I <sub>PP</sub>	Peak Pulse Current(8/20us)	3	A	
T <sub>L</sub>	Maximum lead temperature for soldering during 10s	260	°C	
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C	
T <sub>op</sub>	Operating Temperature Range	-40 to +125	°C	
T <sub>j</sub>	Maximum junction temperature	150	°C	
	IEC61000-4-2 (ESD)	air discharge contact discharge	±25 ±20	KV



### Electrical Characteristics (Ta= 25°C)

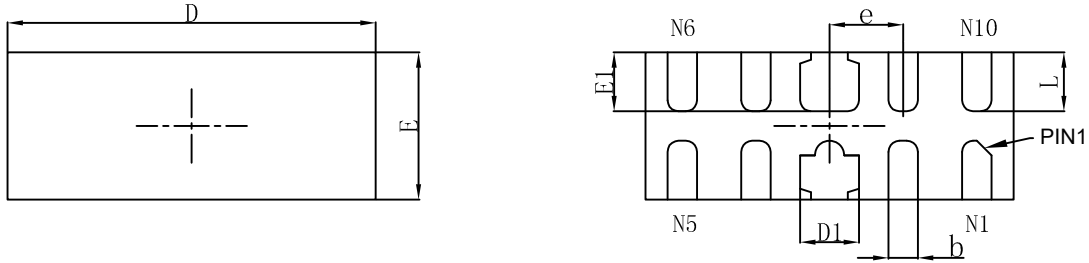
Symbol	Parameter	Test Condition	Min	Typ	Max	Units
$V_{RWM}$	Reverse Working Voltage	Any I/O pin to GND			5.0	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T = 1\text{mA}$ Any I/O pin to GND	6.0	7.5	8.5	V
$I_R$	Reverse Leakage Current	$V_{RWM} = 5.0\text{V}$			1.0	$\mu\text{A}$
$V_C$	Clamping Voltage	$I_{RWM} = 1\text{A}, t_p = 8/20\mu\text{s}$			10	V
		$I_{RWM} = 3\text{A}, t_p = 8/20\mu\text{s}$			15	V
$C_J$	Junction Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$ Any I/O pin to GND		0.4	0.5	pF
$C_J$	Junction Capacitance	$V_R = 0\text{V}, f = 1\text{MHz}$ Any I/O pin to I/O		0.2	0.25	pF

### Typical Characteristics

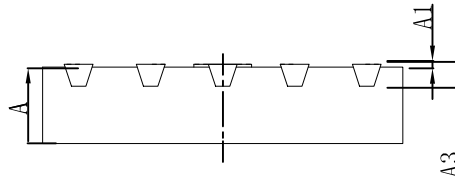




### Outline And Dimensions



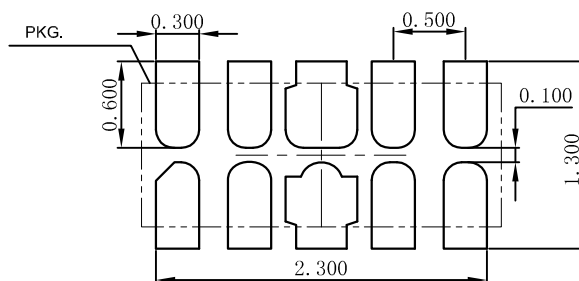
**Bottom View**



**Side View**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.450	0.550	0.017	0.022
A1	0.000	0.050	0.000	0.002
A3	0.152REF.		0.006REF.	
D	2.450	2.550	0.096	0.100
E	0.950	1.050	0.037	0.041
D1	0.350	0.450	0.014	0.018
E1	0.350	0.450	0.014	0.018
b	0.150	0.250	0.006	0.010
e	0.500TYP.		0.020TYP.	
L				

### Soldering Footprint





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